



Material Composition Sheet

Product: GS9029-CTDE3
 Package Type: SOIC - taped (250/reel)
 Manufacturer: Gennum Corporation

Date: 11-Dec-2006

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Chip		1.71	Al	0.01	0.58	5848
			Si	1.70	99.41	994152
			Sub-total:	1.71	99.99	1000000
Die Attach	CRM1076R	0.16	Ag	0.12	75.00	750000
			Epoxy Resin	0.04	25.00	250000
			Sub-total:	0.16	100.00	1000000
Lead Finish External		1.43	Sn	1.43	100.00	1000000
			Sub-total:	1.43	100.00	1000000
Lead Finish Internal		0.30	Ag	0.30	100.00	1000000
			Sub-total:	0.30	100.00	1000000
Leadframe		54.25	Cu	52.89	97.49	974931
			Fe	1.27	2.34	23410
			P	0.02	0.03	369
			Zn	0.07	0.12	1290
			Sub-total:	54.25	99.98	1000000
Marking Ink	Wieder W238	0.01		0.00	0.00	0
			Sub-total:	0.00	0.00	0
Mold Compound	EME G600	95.71	Carbon Black	0.29	0.30	3030
			Epoxy Cresol Novolac	3.83	4.00	40017
			Epoxy Resin	5.45	5.69	56943
			Phenol Resin	4.79	5.00	50047
			SiO2	81.35	84.99	849963
			Sub-total:	95.71	99.98	1000000
Wires	SGA3	0.41	Au	0.41	100.00	1000000
			Sub-total:	0.41	100.00	1000000
Total:		153.98				

GENNUM CORPORATION

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